

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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CPI0806J1R5R-10

UNCONTROLLED **DOCUMENT**

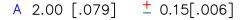
PHYSICAL DIMENSIONS:

3.5

2.5

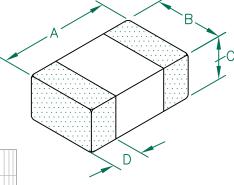
0.5

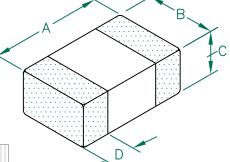
Inductance(uH)



- B 1.60 [.063] ± 0.15[.006]
- ± 0.10[.004] C 0.90 [.035]
- ± 0.20[.008] D 0.50 [.020]

Ls vs Frequency





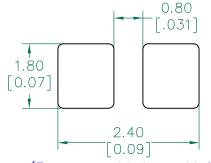


ELECTRICAL CHARACTERISTICS: (μH) @ 1MHz DCR (Ω) I (Max) ± 20% ± 30% Nom 1.5 0.20 1.2 0.14 Min 0.26 1.8 1200mA Max

NOTES: UNLESS OTHERWISE SPECIFIED

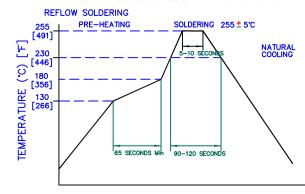
- 1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 3000 PCS/REEL, EMBOSSED PLASTIC TAPE.
- 2. TERMINATION FINISH IS 100% MATTE Sn OVER Ni.
- 3. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
- 4. I (MAX.) IS BASED ON THE MAXIMUM SUSTAINED CURRENT APPLIED WHILE MAINTAINING A MAXIMUM TEMPERATURE RISE OF 40°C OVER AMBIENT.
- 5. OPERATION TEMPERATURE TEMP: -55°C~+125°C (INCLUDING SELF-HEATING)

LAND PATTERNS FOR REFLOW SOLDERING



(For wave soldering, add 0.763 [0.030] to this dimension)

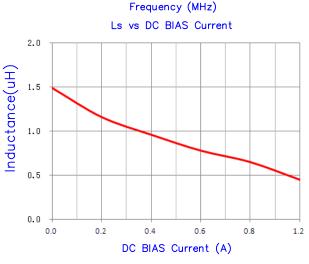
RECOMMENDED SOLDERING CONDITIONS





1.000

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	DIMENSIONS ARE IN mm [INCHE	ES].		This print is the property of Laird Tech. and is loaned in confidence subject to return upon request and					
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				reserved.					
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				CPI0806J1R5R-10		В	co-	-FIRE	QU
В	UPDATE LAIRD LOGO AND NOTES 5	08/05/13	Q	DATE: 03/01/11	SCAL	E: NTS		SHEET:	
Α	ORIGINAL DRAFT	03/01/11	QU	, ,	TOOL		13		
REV	DESCRIPTION	DATE	INT	CPI0806J1R5R-10-B		•	-	2	of 2



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